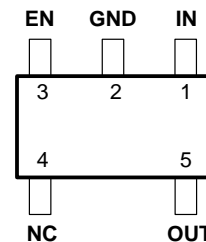


# TPS76030, TPS76032, TPS76033, TPS76038, TPS76050 LOW-POWER 50-mA LOW-DROPOUT LINEAR REGULATORS

SLVS144D – JULY 1998 – REVISED MAY 2001

- 50-mA Low-Dropout Regulator
- Fixed Output Voltage Options: 5 V, 3.8 V, 3.3 V, 3.2 V, and 3 V
- Dropout Typically 120 mV at 50 mA
- Thermal Protection
- Less Than 1- $\mu$ A Quiescent Current in Shutdown
- $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$  Operating Junction Temperature Range
- 5-Pin SOT-23 Package
- ESD Protection Verified to 1.5 kV Human Body Model (HBM) per MIL-STD-883C

DBV PACKAGE  
(TOP VIEW)



NC – No internal connection

## description

The TPS760xx is a 50 mA, low dropout (LDO) voltage regulator designed specifically for battery-powered applications. A proprietary BiCMOS fabrication process allows the TPS760xx to provide outstanding performance in all specifications critical to battery-powered operation.

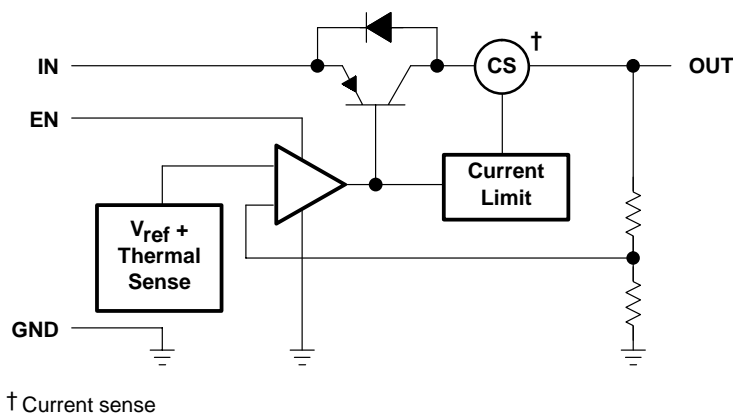
The TPS760xx is available in a space-saving SOT-23 package and operates over a junction temperature range of  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .

AVAILABLE OPTIONS

$T_J$	VOLTAGE	PACKAGE	PART NUMBER	SYMBOL
$-40^{\circ}\text{C}$ to $125^{\circ}\text{C}$	3 V	SOT-23	TPS76030DBVR	PAGI
	3.2 V		TPS76032DBVR	PAOI
	3.3 V		TPS76033DBVR	PAHI
	3.8 V		TPS76038DBVR	PAJI
	5 V		TPS76050DBVR	PANI

NOTE: The DBV package is available taped and reeled only.

## functional block diagram



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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# TPS76030, TPS76032, TPS76033, TPS76038, TPS76050

## LOW-POWER 50-mA LOW-DROPOUT LINEAR REGULATORS

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### Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
EN	3	I	Enable input
GND	2		Ground
IN	1	I	Input voltage
NC	4		No connection
OUT	5	O	Regulated output voltage

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Input voltage range, $V_I$ <sup>‡</sup>	–0.3 V to 16 V
Voltage range at EN	–0.3 V to $V_I + 0.3$ V
Peak output current	internally limited
Continuous total dissipation	See Dissipation Rating Table
Operating junction temperature range, $T_J$	–40°C to 150°C
Storage temperature range, $T_{stg}$	–65°C to 150°C
ESD rating, HBM	1.5 kV

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>‡</sup> All voltages are with respect to device GND pin.

DISSIPATION RATING TABLE

BOARD	PACKAGE	$R_{\theta JC}$	$R_{\theta JA}$	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A \leq 25^\circ\text{C}$ POWER RATING	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING
Low K <sup>§</sup>	DBV	65.8 °C/W	259 °C/W	3.9 mW/°C	386 mW	212 mW	154 mW
High K <sup>¶</sup>	DBV	65.8 °C/W	180 °C/W	5.6 mW/°C	555 mW	305 mW	222 mW

<sup>§</sup> The JEDEC Low K (1s) board design used to derive this data was a 3 inch x 3 inch, two layer board with 2 ounce copper traces on top of the board.

<sup>¶</sup> The JEDEC High K (2s2p) board design used to derive this data was a 3 inch x 3 inch, multilayer board with 1 ounce internal power and ground planes and 2 ounce copper traces on top and bottom of the board.

### recommended operating conditions

		MIN	NOM	MAX	UNIT
Input voltage, $V_I$	TPS76030	3.2		16	V
	TPS76032	3.4		16	
	TPS76033	3.5		16	
	TPS76038	4		16	
	TPS76050	5.2		16	
Continuous output current, $I_O$		0		50	mA
Operating junction temperature, $T_J$		–40		125	°C



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# TPS76030, TPS76032, TPS76033, TPS76038, TPS76050

## LOW-POWER 50-mA LOW-DROPOUT LINEAR REGULATORS

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**electrical characteristics over recommended operating free-air temperature range,  
 $V_I = V_{O(nom)} + 1\text{ V}$ ,  $I_O = 1\text{ mA}$ ,  $EN = V_I$ ,  $C_O = 2.2\text{ }\mu\text{F}$  (unless otherwise noted)**

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
V <sub>O</sub>	Output voltage	TPS76030	T <sub>J</sub> = 25°C	2.96	3	3.04	V
		T <sub>J</sub> = 25°C, 1 mA < I <sub>O</sub> < 50 mA	2.92		3.04		
		1 mA < I <sub>O</sub> < 50 mA	2.91		3.07		
	TPS76032	T <sub>J</sub> = 25°C	3.16	3.2	3.24	V	
		T <sub>J</sub> = 25°C, 1 mA < I <sub>O</sub> < 50 mA	3.13		3.24		
		1 mA < I <sub>O</sub> < 50 mA	3.1		3.3		
	TPS76033	T <sub>J</sub> = 25°C	3.26	3.3	3.34	V	
		T <sub>J</sub> = 25°C, 1 mA < I <sub>O</sub> < 50 mA	3.23		3.34		
		1 mA < I <sub>O</sub> < 50 mA	3.2		3.4		
	TPS76038	T <sub>J</sub> = 25°C	3.76	3.8	3.84	V	
		T <sub>J</sub> = 25°C, 1 mA < I <sub>O</sub> < 50 mA	3.73		3.84		
		1 mA < I <sub>O</sub> < 50 mA	3.7		3.9		
	TPS76050	T <sub>J</sub> = 25°C	4.95	5	5.05	V	
		T <sub>J</sub> = 25°C, 1 mA < I <sub>O</sub> < 50 mA	4.91		5.05		
		1 mA < I <sub>O</sub> < 50 mA	4.89		5.1		
I <sub>I(standby)</sub>	Standby current	EN = 0 V			1	μA	
Quiescent current (GND current)		I <sub>O</sub> = 0 mA, T <sub>J</sub> = 25°C		90	115	μA	
		I <sub>O</sub> = 0 mA			130		
		I <sub>O</sub> = 1 mA, T <sub>J</sub> = 25°C		100	130		
		I <sub>O</sub> = 1 mA			170		
		I <sub>O</sub> = 10 mA, T <sub>J</sub> = 25°C		190	215		
		I <sub>O</sub> = 10 mA			260		
		I <sub>O</sub> = 50 mA, T <sub>J</sub> = 25°C		850	1100		
		I <sub>O</sub> = 50 mA			1200		
Input regulation	TPS76030	4 V < V <sub>I</sub> < 16, I <sub>O</sub> = 1 mA		3	10	mV	
	TPS76032	4.2 V < V <sub>I</sub> < 16, I <sub>O</sub> = 1 mA		3	10		
	TPS76033	4.3 V < V <sub>I</sub> < 16, I <sub>O</sub> = 1 mA		3	10		
	TPS76038	4.8 V < V <sub>I</sub> < 16, I <sub>O</sub> = 1 mA		3	10		
	TPS76050	6 V < V <sub>I</sub> < 16, I <sub>O</sub> = 1 mA		3	10		
V <sub>n</sub>	Output noise voltage	BW = 300 Hz to 50 kHz, C <sub>O</sub> = 10 μF, T <sub>J</sub> = 25°C		190		μVrms	
Ripple rejection		f = 1 kHz, C <sub>O</sub> = 10 μF, T <sub>J</sub> = 25°C		63		dB	
Dropout voltage		I <sub>O</sub> = 0 mA T <sub>J</sub> = 25°C		1	3	mV	
		I <sub>O</sub> = 0 mA			5		
		I <sub>O</sub> = 1 mA, T <sub>J</sub> = 25°C		7	10		
		I <sub>O</sub> = 1 mA			15		
		I <sub>O</sub> = 10 mA, T <sub>J</sub> = 25°C		40	60		
		I <sub>O</sub> = 10 mA			90		
		I <sub>O</sub> = 50 mA T <sub>J</sub> = 25°C		120	150		
		I <sub>O</sub> = 50 mA			180		
Peak output current/current limit			100	125	135	mA	
High level enable input			2			V	
Low level enable input					0.8	V	
I <sub>I</sub>	Input current (EN)	EN = 0 V	-1	0	1	μA	
		EN = V <sub>I</sub>		2.5	5	μA	



# TPS76030, TPS76032, TPS76033, TPS76038, TPS76050

## LOW-POWER 50-mA LOW-DROPOUT LINEAR REGULATORS

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### Table of Graphs

			FIGURE
$V_O$	Output voltage	vs Output current	1, 2, 3
		vs Free-air temperature	4, 5, 6
	Ground current	vs Free-air temperature	7, 8, 9
	Output noise	vs Frequency	10
$Z_O$	Output impedance	vs Frequency	11
$V_{DO}$	Dropout voltage	vs Free-air temperature	12
	Line transient response		13, 15
	Load transient response		14, 16

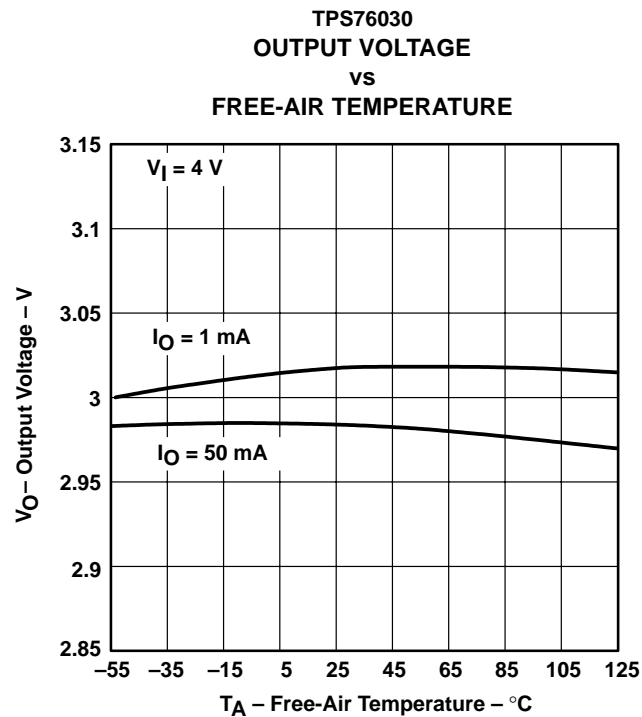
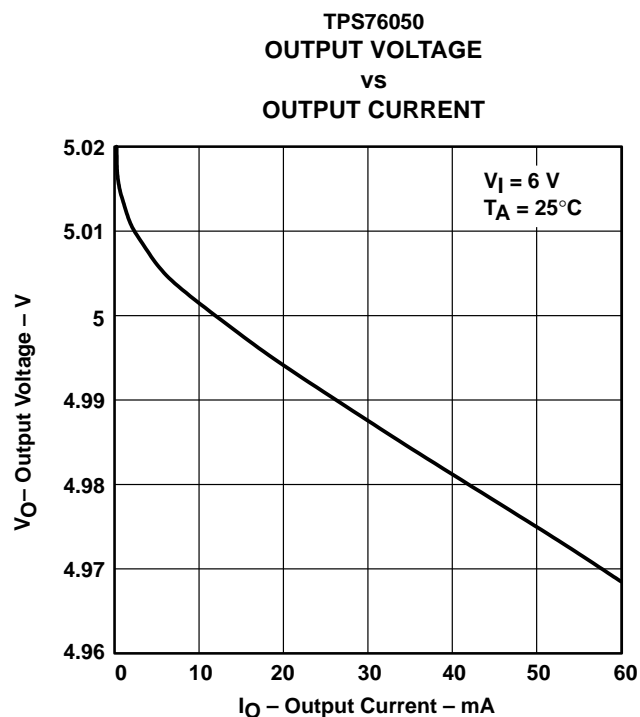
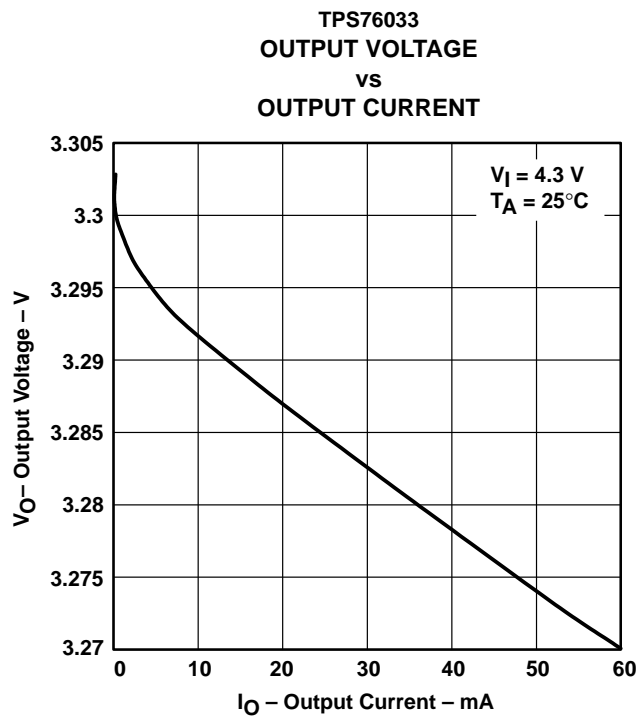
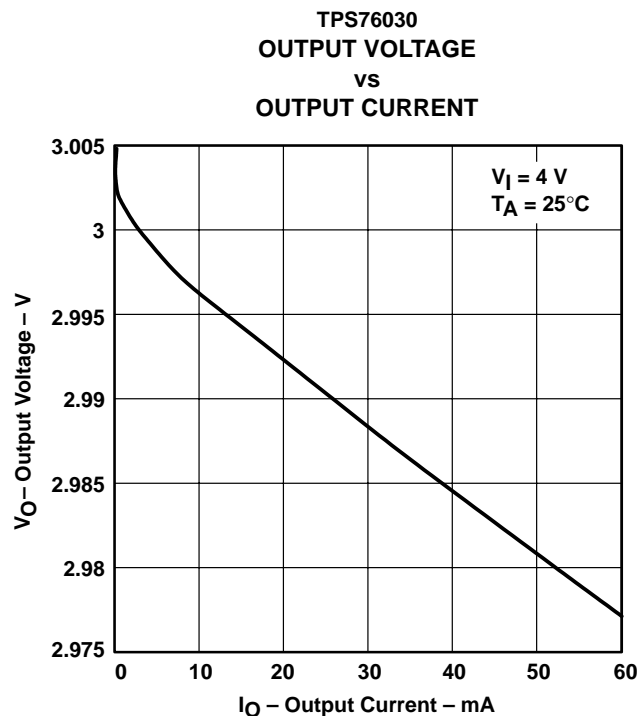


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# TPS76030, TPS76032, TPS76033, TPS76038, TPS76050 LOW-POWER 50-mA LOW-DROPOUT LINEAR REGULATORS

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## TYPICAL CHARACTERISTICS



# TPS76030, TPS76032, TPS76033, TPS76038, TPS76050

## LOW-POWER 50-mA LOW-DROPOUT LINEAR REGULATORS

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### TYPICAL CHARACTERISTICS

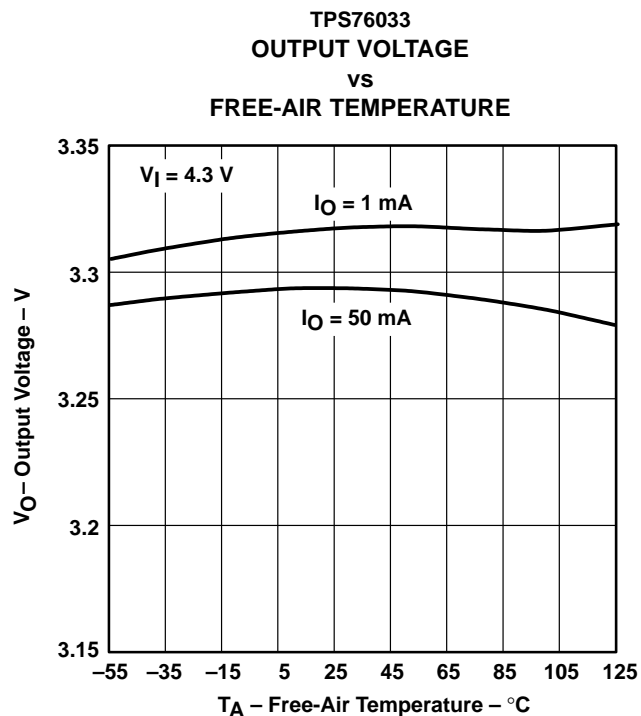


Figure 5

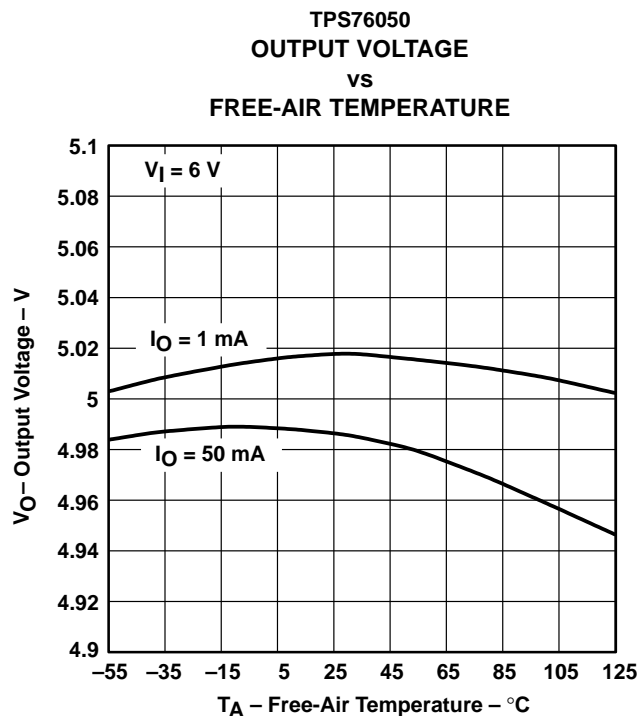


Figure 6

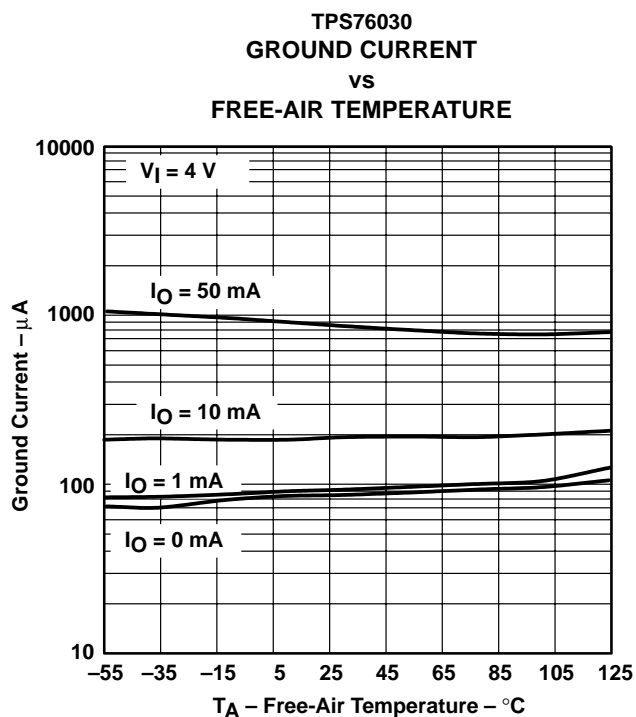


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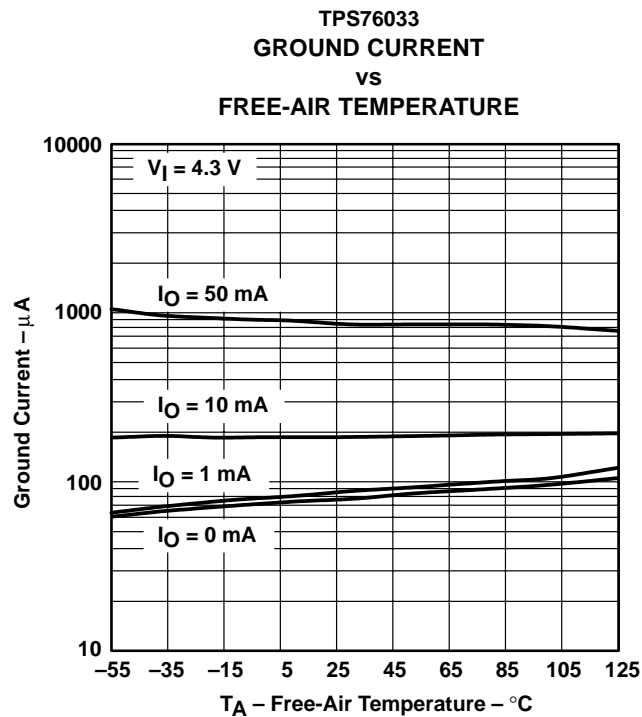


Figure 8

# TYPICAL CHARACTERISTICS

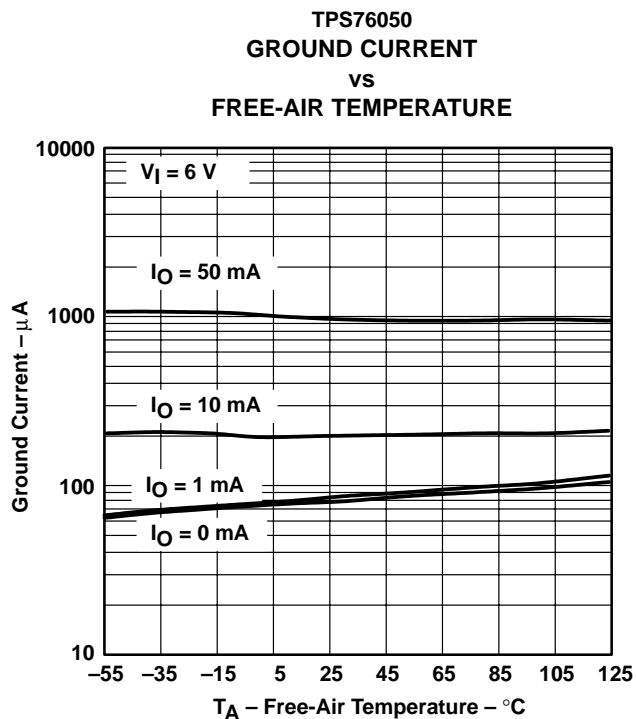


Figure 9

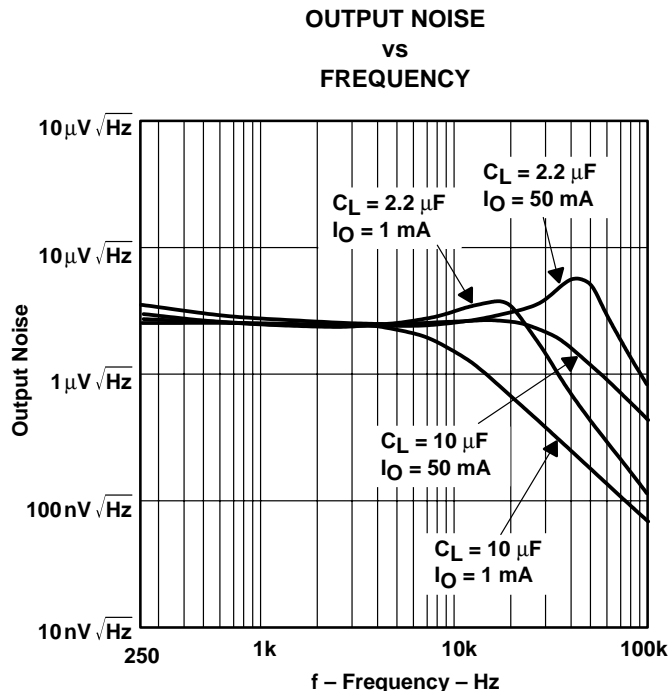


Figure 10

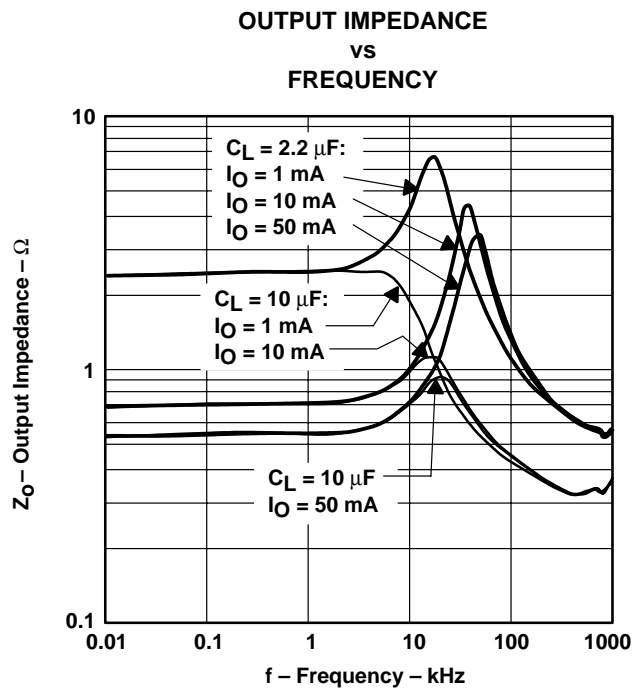


Figure 11

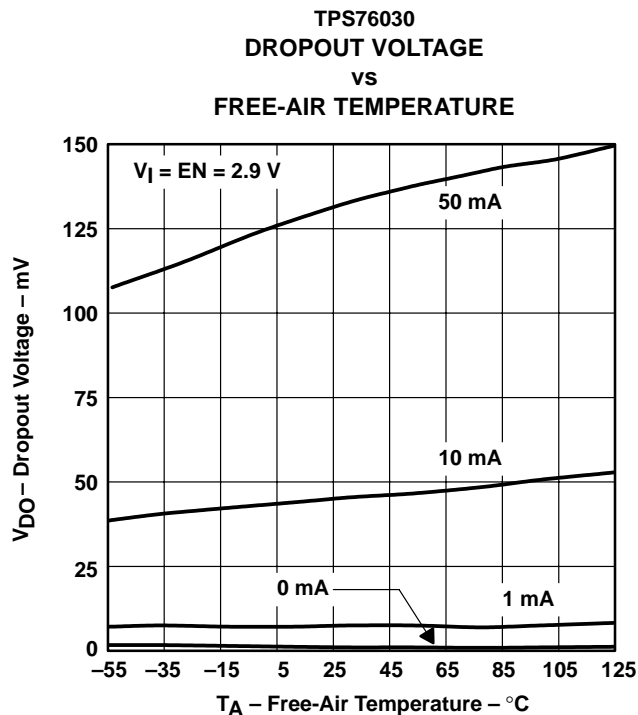


Figure 12

# TPS76030, TPS76032, TPS76033, TPS76038, TPS76050

## LOW-POWER 50-mA LOW-DROPOUT LINEAR REGULATORS

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### TYPICAL CHARACTERISTICS

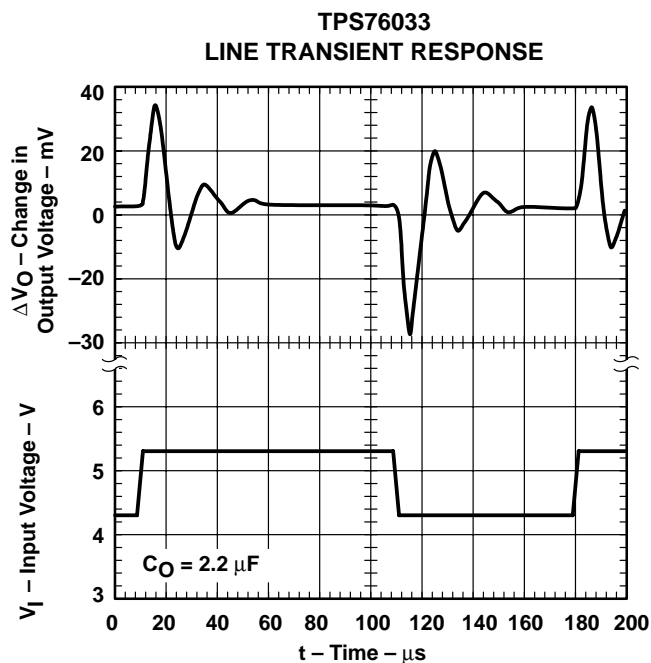


Figure 13

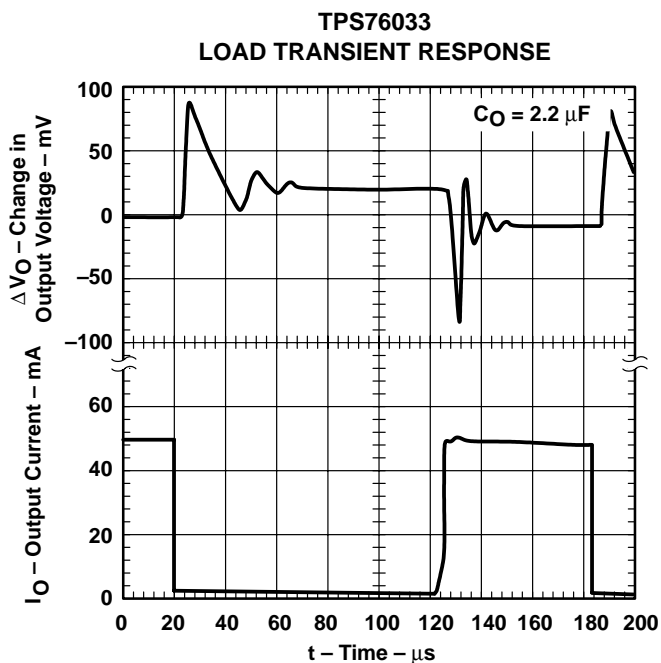


Figure 14

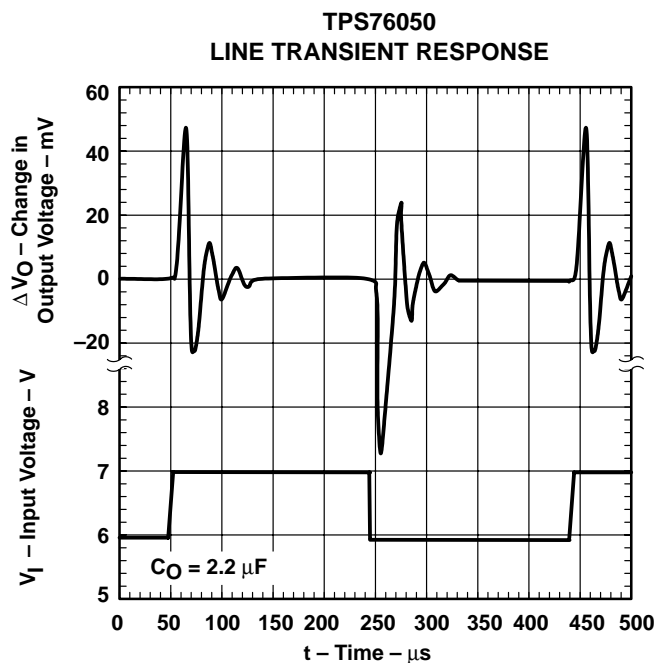


Figure 15

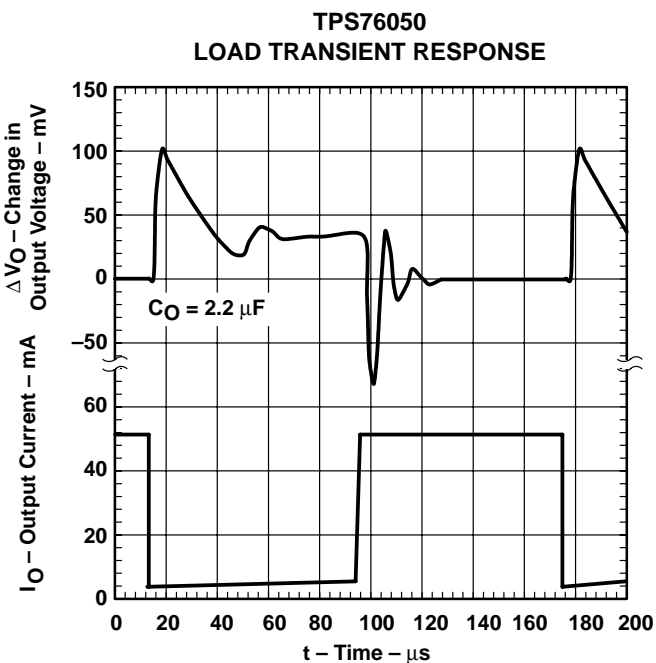


Figure 16



## APPLICATION INFORMATION

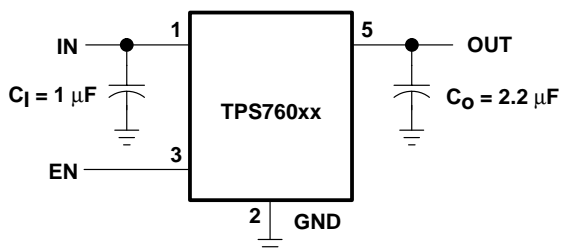


Figure 17. TPS760xx Typical Application

### over current protection

The over current protection circuit forces the TPS760xx into a constant current output mode when the load is excessive or the output is shorted to ground. Normal operation resumes when the fault condition is removed. An overload or short circuit may also activate the over temperature protection if the fault condition persists.

### over temperature protection

The thermal protection system shuts the TPS760xx down when the junction temperature exceeds 160°C. The device recovers and operates normally when the temperature drops below 155°C.

### input capacitor

A 0.047 µF or larger ceramic decoupling capacitor with short leads connected between IN and GND is recommended. The decoupling capacitor may be omitted if there is a 1 µF or larger electrolytic capacitor connected between IN and GND and located reasonably close to the TPS760xx. However, the small ceramic device is desirable even when the larger capacitor is present, if there is a lot of high frequency noise present in the system.

### output capacitor

Like all low dropout regulators, the TPS760xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 2.2 µF and the ESR (equivalent series resistance) must be between 0.1 Ω and 20 Ω. Capacitor values of 2.5-µF or larger are acceptable, provided the ESR is less than 20 Ω. Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Most of the commercially available 2.2-µF surface-mount solid-tantalum capacitors, including devices from Sprague, Kemet, and Nichicon, meet the ESR requirements stated above. Multilayer ceramic capacitors should have minimum values of 2.5 µF over the full operating temperature range of the equipment.

### enable (EN)

A logic zero on the enable input shuts the TPS760xx off and reduces the supply current to less than 1 µA. Pulling the enable input high causes normal operation to resume. If the enable feature is not used, EN should be connected to IN to keep the regulator on all of the time. The EN input must not be left floating.

### reverse current path

The power transistor used in the TPS760xx has an inherent diode connected between IN and OUT as shown in the functional block diagram. This diode conducts current from the OUT terminal to the IN terminal whenever IN is lower than OUT by a diode drop. This condition does not damage the TPS760xx, provided the current is limited to 100 mA.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS76030DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAGI	<a href="#">Samples</a>
TPS76030DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAGI	<a href="#">Samples</a>
TPS76030DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAGI	<a href="#">Samples</a>
TPS76030DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAGI	<a href="#">Samples</a>
TPS76032DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAOI	<a href="#">Samples</a>
TPS76032DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAOI	<a href="#">Samples</a>
TPS76033DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAHI	<a href="#">Samples</a>
TPS76033DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAHI	<a href="#">Samples</a>
TPS76033DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAHI	<a href="#">Samples</a>
TPS76033DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAHI	<a href="#">Samples</a>
TPS76038DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAJI	<a href="#">Samples</a>
TPS76038DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAJI	<a href="#">Samples</a>
TPS76038DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAJI	<a href="#">Samples</a>
TPS76038DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAJI	<a href="#">Samples</a>
TPS76050DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PANI	<a href="#">Samples</a>
TPS76050DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PANI	<a href="#">Samples</a>
TPS76050DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PANI	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS76050DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PANI	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS76030DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76030DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76032DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76033DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76033DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76038DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76038DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76050DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76050DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

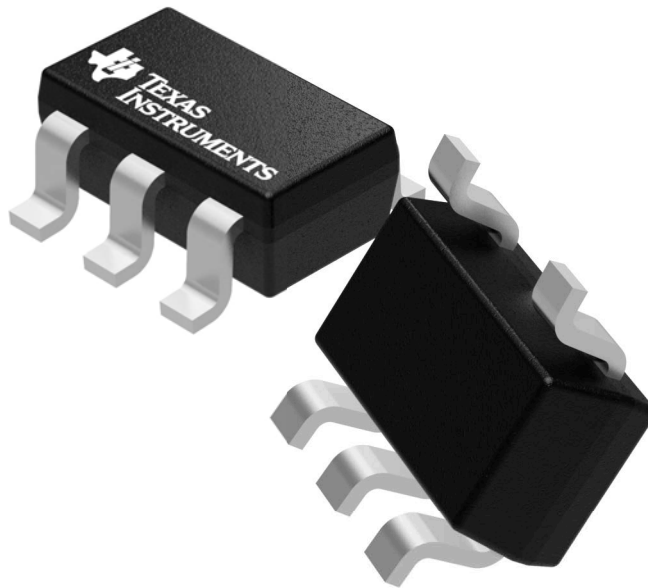
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS76030DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76030DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS76032DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76033DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76033DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS76038DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76038DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS76050DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76050DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0

## GENERIC PACKAGE VIEW

**DBV 5**

**SOT-23 - 1.45 mm max height**

SMALL OUTLINE TRANSISTOR



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4073253/P

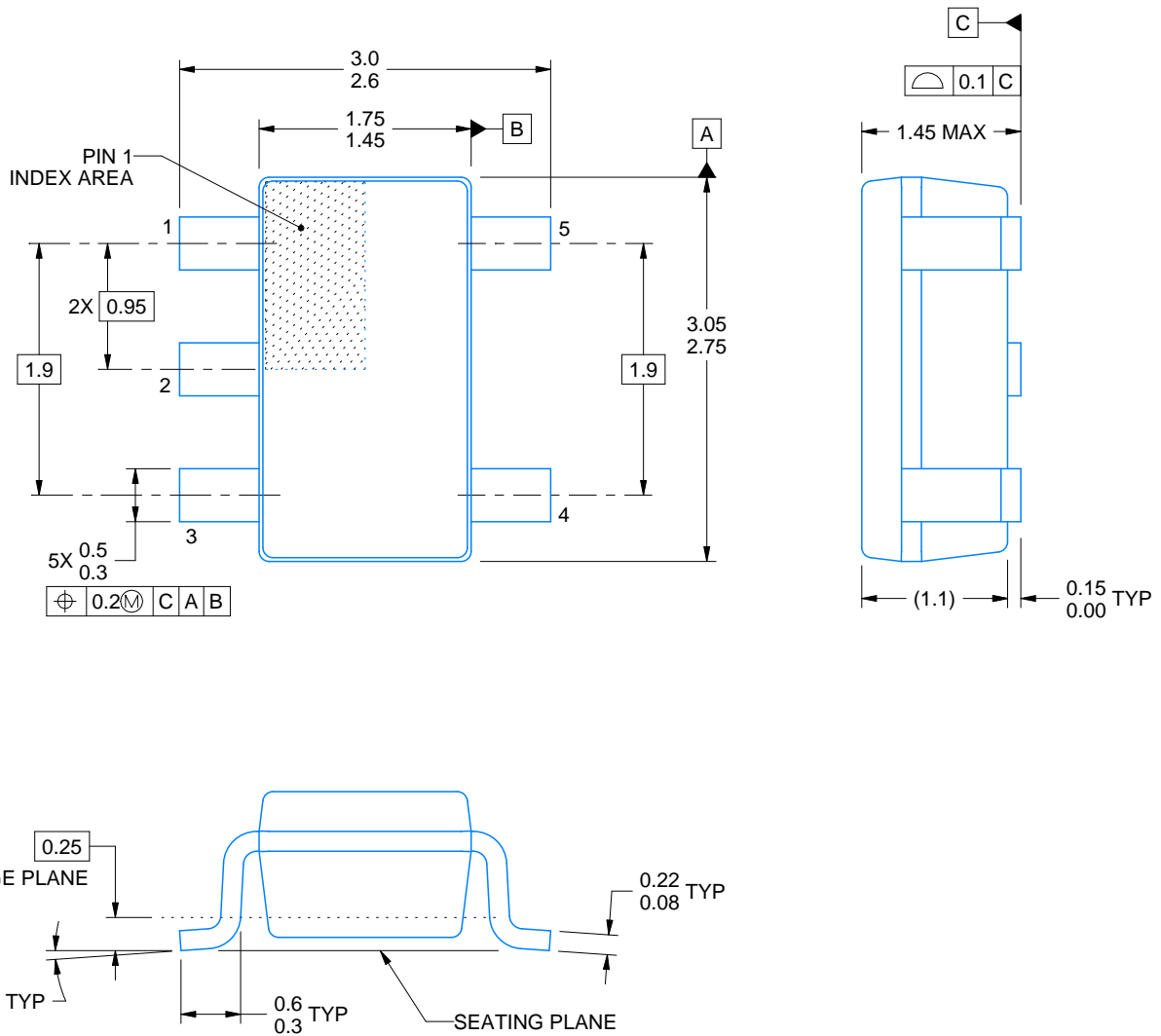


**DBV0005A**

# PACKAGE OUTLINE

**SOT-23 - 1.45 mm max height**

SMALL OUTLINE TRANSISTOR



4214839/C 04/2017

## NOTES:

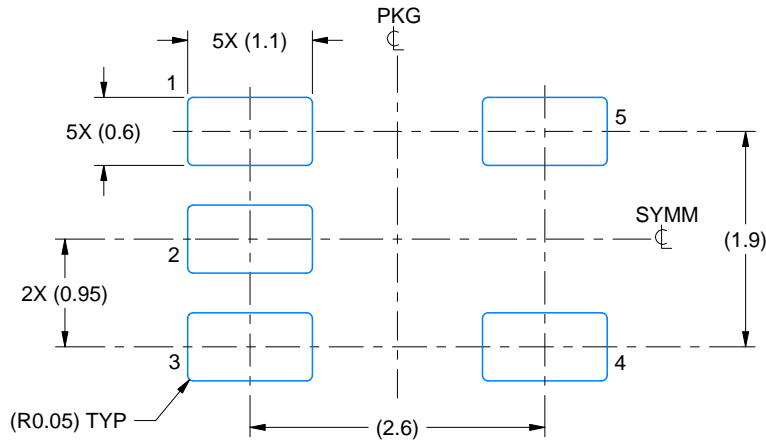
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-178.

# EXAMPLE BOARD LAYOUT

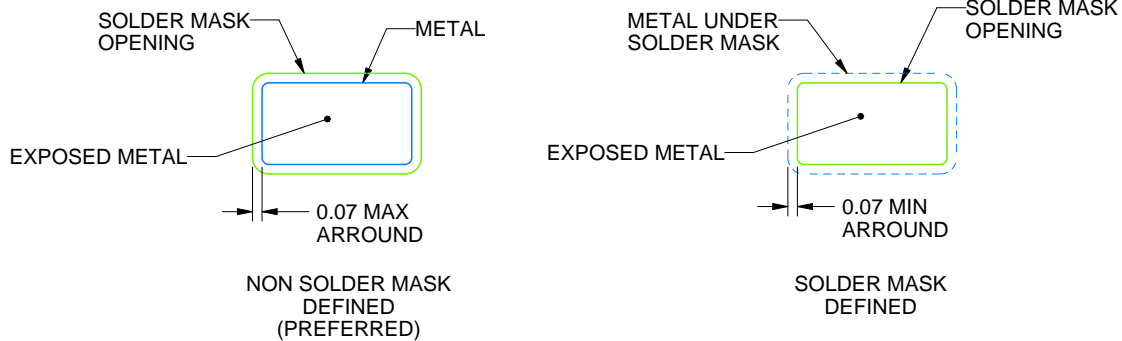
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

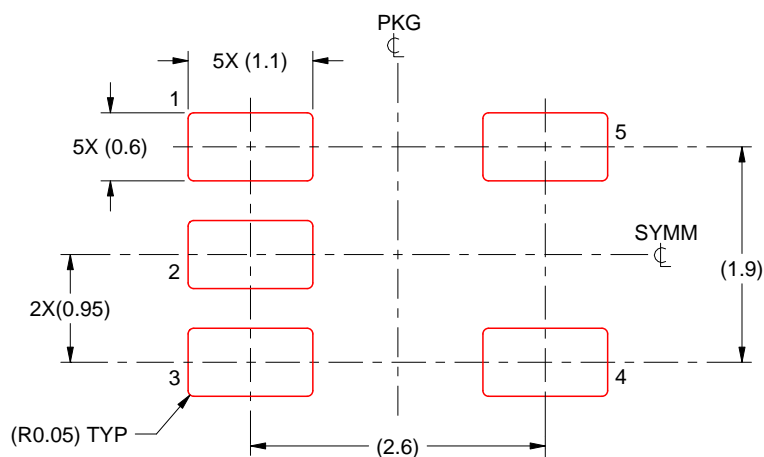


## EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.

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